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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10066645	FILING DATE 02/06/2002	CLASS 438	SUBCLASS 630	GAH 2841	EXAMINER NEMA PEREZ NY
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\*\*APPLICANTS: Kellar Scot; Kim Sarah; List R.;

\*\*CONTINUING DATA VERIFIED:

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\*\* FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed	<input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO
35 USC 119 conditions met	<input type="checkbox"/> yes <input type="checkbox"/> no	219.40606X00
Verified and Acknowledged Examiners's initials		
TITLE : Dielectric recess for wafer-to-wafer and die-to-die metal bonding and method of fabricating the same.		

U.S. DEPT. OF COMMERCE / PAT. & TM. PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner	DRAWING	
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Applicant Examiner	
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